

Metal Foil Current Sense Resistors, Very High Power (to 2 W)



FEATURES

- Ultra low sensing resistance minimizes power dissipation, improving efficiency
- Wide side terminal construction (0508 and 0612) for lower ESL
- High power to foot print size ratio (2 W in 0612 and 0.5 W in 0508)
- Sulfur resistant
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

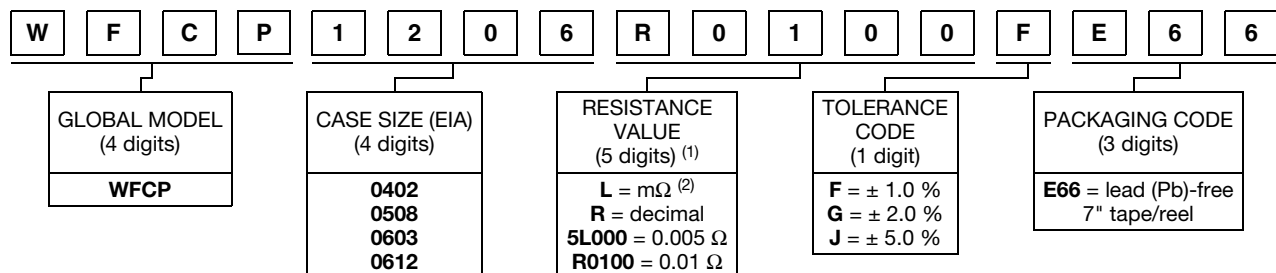
- Switching power supply
- Voltage regulation module
- DC/DC converter, adaptor, battery pack, charger
- Pad and cell phone
- Power management

STANDARD ELECTRICAL SPECIFICATIONS

GLOBAL MODEL	SIZE	POWER RATING W	TOLERANCE %	RESISTANCE VALUE RANGE Ω	WEIGHT (typical) g/1000 pieces
WFCP0402	0402	0.25	$\pm 1, \pm 2, \pm 5$	0.0025 to 0.050	1.1
WFCP0508	0508	0.5	$\pm 1, \pm 2, \pm 5$	0.005 to 0.03	6.8
WFCP0603	0603	0.5	$\pm 1, \pm 2, \pm 5$	0.002 to 0.03	3.3
WFCP0612	0612	1.0	$\pm 1, \pm 2, \pm 5$	0.0051 to 0.03	14.7
	0612	2.0	$\pm 1, \pm 2, \pm 5$	0.001 to 0.005	14.7

GLOBAL PART NUMBER INFORMATION

Global Part Numbering Example: WFCP1206R0100FE66



Notes

- ⁽¹⁾ Resistance values are available per E12 and E24 decades; www.vishay.com/doc?28372
⁽²⁾ Use "L" for resistance values < 0.01 Ω

TECHNICAL SPECIFICATIONS					
PARAMETER	UNIT	RESISTOR CHARACTERISTICS			
		WFCP0402	WFCP0508	WFCP0603	WFCP0612
Temperature coefficient	ppm/°C	± 100 for 5.1 mΩ to 50 mΩ	± 75 for 5 mΩ to 30 mΩ	± 75 for 10 mΩ to 30 mΩ	± 75 for 5.1 mΩ to 30 mΩ
		± 150 for 2.5 mΩ to 5 mΩ		± 100 for 2 mΩ to 9 mΩ	± 100 for 1 mΩ to 5 mΩ
Operating temperature range	°C	-55 to +170			
Maximum working voltage	V	$(P \times R)^{1/2}$			
Maximum element temperature	°C	170			

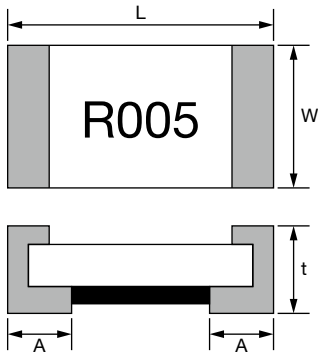
DIMENSIONS in inches (millimeters)


Fig. 1

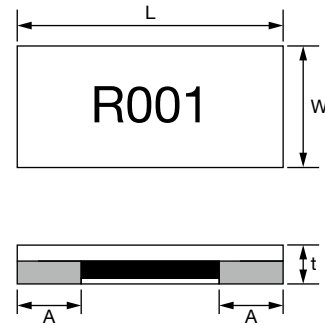
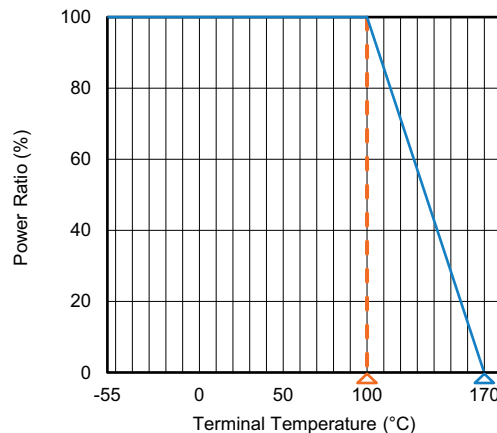


Fig. 2

TYPE (INCH SIZE)	RESISTANCE RANGE (mΩ)	DIMENSIONS (in millimeters)				DIMENSIONS FIG.
		L	W	t	A	
WFCP0402	2.5 to 5	1.00 ± 0.1	0.55 ± 0.1	0.45 ± 0.10	0.45 ± 0.1	1
	5 to 7				0.35 ± 0.1	1
	8 to 50				0.25 ± 0.1	1
WFCP0508	5 to 30	1.30 ± 0.2	2.0 ± 0.20	0.60 ± 0.20	0.30 ± 0.2	1
WFCP0603	2 to 30	1.60 ± 0.1	0.80 ± 0.1	0.55 ± 0.15	0.30 ± 0.2	1
WFCP0612	1 to 5	1.60 ± 0.2	3.20 ± 0.20	0.75 ± 0.25	0.30 ± 0.2	2
	5 to 30			0.60 ± 0.20		1

Note

- 0402 has no marking; 0508, 0603, and 0612 marking shows two digits for resistance

DERATING


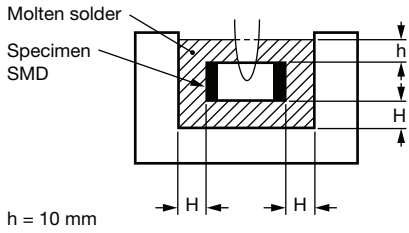
PERFORMANCES

ENVIRONMENTAL PERFORMANCE			
NO.	ITEM	TEST CONDITION	SPECIFICATION
1 ⁽¹⁾	Short time overload	5 times rated power for 5 seconds (JIS-C5202-5.5)	$\Delta R: \pm (1 \% + 0.0005 \Omega)$
2	Temperature coefficient of resistance (TCR)	+25 °C / +125 °C (JIS-C5202-5.2) $TCR (\text{ppm}/^\circ\text{C}) = \frac{\Delta R}{R \times \Delta t} \times 10^6$	Refer to Electrical Specification
3	Damp heat with load	The specimens shall be placed in a chamber and subjected to a relative humidity of 90 % to 95 % and a temperature of 40 °C ± 2 °C for the period of 1000 hours with applying rated power 1.5 hours ON and 0.5 hour OFF. (MIL-STD-202, method 103)	$\Delta R: \pm (1 \% + 0.0005 \Omega)$
4	High temperature exposure	The chip (mounted on board) is exposed in the heat chamber 125 °C ± 3 °C for 1000 hours. (JIS-C5202-7.2)	$\Delta R: \pm (1 \% + 0.0005 \Omega)$
5	Load life	Apply rated power at 70 °C ± 2 °C for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	$\Delta R: \pm (1 \% + 0.0005 \Omega)$
6	Rapid change of temperature	The chip (mounted on board) is exposed, -55 °C ± 3 °C (30 min.) / +155 °C ± 2 °C (30 min.) for 5 cycles. The following conditions as the following figure. (JIS-C5202-7.4) Ambient temperature 30 min. 30 min. +155 (± 2) °C +25 (± 2) °C -55 (± 3) °C 2 to 3 min. 1 cycle	$\Delta R: \pm (1 \% + 0.0005 \Omega)$

Note

⁽¹⁾ WFPC0612 short term overload is 3 times for 5 seconds

FUNCTION PERFORMANCE			
NO.	ITEM	TEST CONDITION	SPECIFICATION
1	Bending strength	Mount the chip to test substrate. Apply pressure in direction of arrow unit band width reaches 2 mm (+0.2 / -0 mm) illustrated in the figure below and hold for 10 s ± 1 s. (JIS-C5202-6.1) Unit: mm 20 1.6 Amount of bend Testing printed circuit board Jig Position before bend	$\Delta R: \pm (1 \% + 0.0005 \Omega)$
2	Solvent resistance	Complete immersion of specimens in isopropyl alcohol for 3 (+5, -0) min. 25 °C ± 5 °C. (MIL-STD-202, method 215)	Verify marking permanency. (not required for laser etched parts or parts with no marking)
3	Resistance to solder heat	The specimen chip shall be immersed into the flux specified in the solder bath 260 °C ± 5 °C for 10 s ± 1 s. (MIL-STD-202, method 210)	$\Delta R: \pm (1 \% + 0.0005 \Omega)$

FUNCTION PERFORMANCE			
NO.	ITEM	TEST CONDITION	SPECIFICATION
4	Solderability	<p>The specimen chip shall be immersed into the flux specified in the solder bath $235\text{ }^{\circ}\text{C} \pm 5\text{ }^{\circ}\text{C}$ for $2\text{ s} \pm 0.5\text{ s}$. It shall be immersed to a point 10 mm from its root. (Sn96.5 / Ag3.0 / Cu0.5) (JIS-C5 202-6.11)</p>  <p>h = 10 mm H = 10 mm min.</p>	Solder shall be covered 95 % or more of the electrode area.

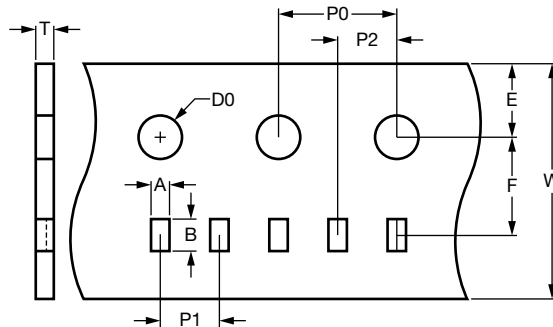
Notes

- The surface temperature of component should below $100\text{ }^{\circ}\text{C}$
- 0.5 W with total solder pad trace size of 100 mm^2
- 1.0 W with total solder pad trace size of 150 mm^2
- 2.0 W with total solder pad trace size of 300 mm^2
- 3.0 W with total solder pad trace size of 450 mm^2

TAPE PACKAGING SPECIFICATIONS			
MODEL	REEL		
	TAPE WIDTH	DIAMETER	PIECES / REEL
WFCP0402	Embossed paper tape	178 mm / 7"	10 000
WFCP0508 WFCP0603 WFCP0612	Embossed paper tape	178 mm / 7"	5000

Note

- Embossed carrier tape per EIA (EIAJ)

PAPER TAPE SPECIFICATIONS


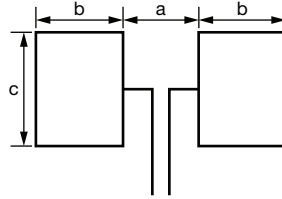
TYPE	CARRIER DIMENSIONS (in millimeters)									
	A	B	E	F	W	P0	P1	P2	D0	T
WFCP0402	0.7 ± 0.05	1.2 ± 0.05	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	2.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.6 ± 0.1
WFCP0508	1.6 ± 0.1	2.4 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.97 ± 0.1
WFCP0603	1.1 ± 0.1	1.9 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.70 ± 0.1
WFCP0612	2.0 ± 0.1	3.6 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.97 ± 0.1

Notes

- Embossed carrier tape per EIA (EIAJ)
- Additional packaging details at www.vishay.com/doc?20051

STORAGE CONDITIONS

Temperature: 5 °C to 35 °C, humidity: 40 % to 75 %

RECOMMENDED SOLDER PAD LAYOUT


TYPE	PAD LAYOUT DIMENSIONS (in millimeters)		
	a	b	c
0402 (8 mΩ to 50 mΩ)	0.50	0.50	0.60
0402 (2.5 mΩ to 7 mΩ)	0.30	0.60	0.60
0508 (5 mΩ to 30 mΩ)	0.50	1.30	2.60
0603 (2 mΩ to 9 mΩ)	0.60	0.90	1.00
0603 (9.1 mΩ to 30 mΩ)	0.90	0.70	1.00
0612 (5.1 mΩ to 30 mΩ)	0.60	1.30	3.60
0612 (1 mΩ to 5 mΩ)	0.60	1.30	3.80

Note

- Recommend to use the steel plate which thickness > 100 μm to avoid the insufficient solder height

SOLDERING RECOMMENDATIONS

- Peak reflow temperatures and durations:
 - IR reflow peak = 260 °C max. for 10 s
 - Wave solder = 260 °C max. for 10 s
- Compatible with lead and lead (Pb)-free solder reflow processes
- Recommended IR reflow profile for surface mount devices: www.vishay.com/doc?31052



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